



Material Content Data Sheet



Sales Product Name		TLE4941C		Issued		1. August 2018		
MA#		MA000862086						
Package		PG-SSO-2-4		Weight*		168.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.278	1.35	1.35	13489	13489
leadframe	non noble metal	chromium	7440-47-3	0.288	0.17		1705	
	non noble metal	titanium	7440-32-6	0.288	0.17		1705	
	non noble metal	nickel	7440-02-0	0.384	0.23		2273	
	non noble metal	tin	7440-31-5	0.576	0.34		3410	
	non noble metal	copper	7440-50-8	94.449	55.93	56.84	559233	568326
wire	noble metal	gold	7440-57-5	0.042	0.02	0.02	249	249
encapsulation	organic material	carbon black	1333-86-4	0.451	0.27		2672	
	plastics	brominated resin	-	0.564	0.33		3341	
	inorganic material	antimonytrioxide	1309-64-4	1.128	0.67		6681	
	plastics	epoxy resin	-	10.268	6.08		60799	
	inorganic material	silicondioxide	60676-86-0	44.007	26.06	33.41	260565	334058
leadfinish	non noble metal	tin	7440-31-5	6.247	3.70	3.70	36988	36988
plating	noble metal	silver	7440-22-4	0.986	0.58	0.58	5836	5836
glue	plastics	epoxy resin	-	0.149	0.09		881	
	noble metal	silver	7440-22-4	0.595	0.35	0.44	3522	4403
smd	inorganic material	leadoxide	1317-36-8	0.001	0.00		7	
	inorganic material	leadtitanate	12060-00-3	0.031	0.02		183	
	inorganic material	titandioxide	13463-67-7	0.148	0.09		876	
	inorganic material	bismuth trioxide	1304-76-3	0.255	0.15		1510	
	noble metal	palladium	7440-05-3	0.474	0.28		2808	
	noble metal	silver	7440-22-4	1.491	0.88		8829	
	inorganic material	bariumtitanate	12047-27-7	3.790	2.24	3.66	22438	36651
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7 (c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

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